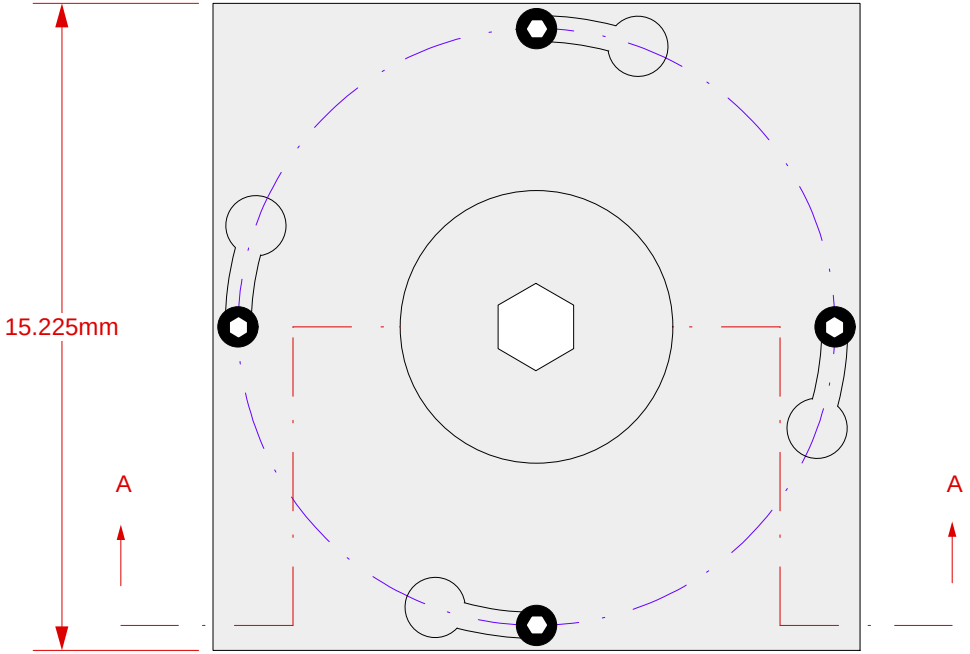
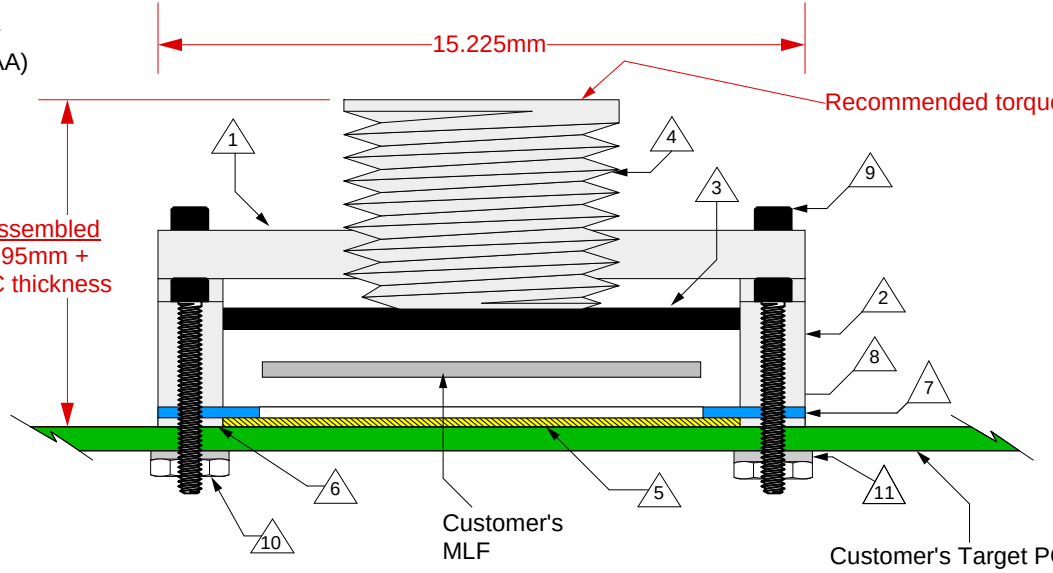
GHz MLF Socket - Direct mount, solderless

Top View



Side View
(Section AA)



Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- IC guide prevents over compression of elastomer
- Easily removable swivel socket lid

1	Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
2	Socket base: Black anodized Aluminum. Thickness = 3mm.
3	Compression Plate: Black anodized Aluminum. Thickness = 1.5mm.
4	Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 3mm.
5	Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
6	Elastomer Guide: Cirlex Thickness = 0.475mm.
7	IC (MLF) Guide: Torlon 4203
8	Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread , 9.525mm long.
9	Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
10	Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
11	Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

SG-MLF-7014 Drawing	Status: Released	Scale: -	Rev: G
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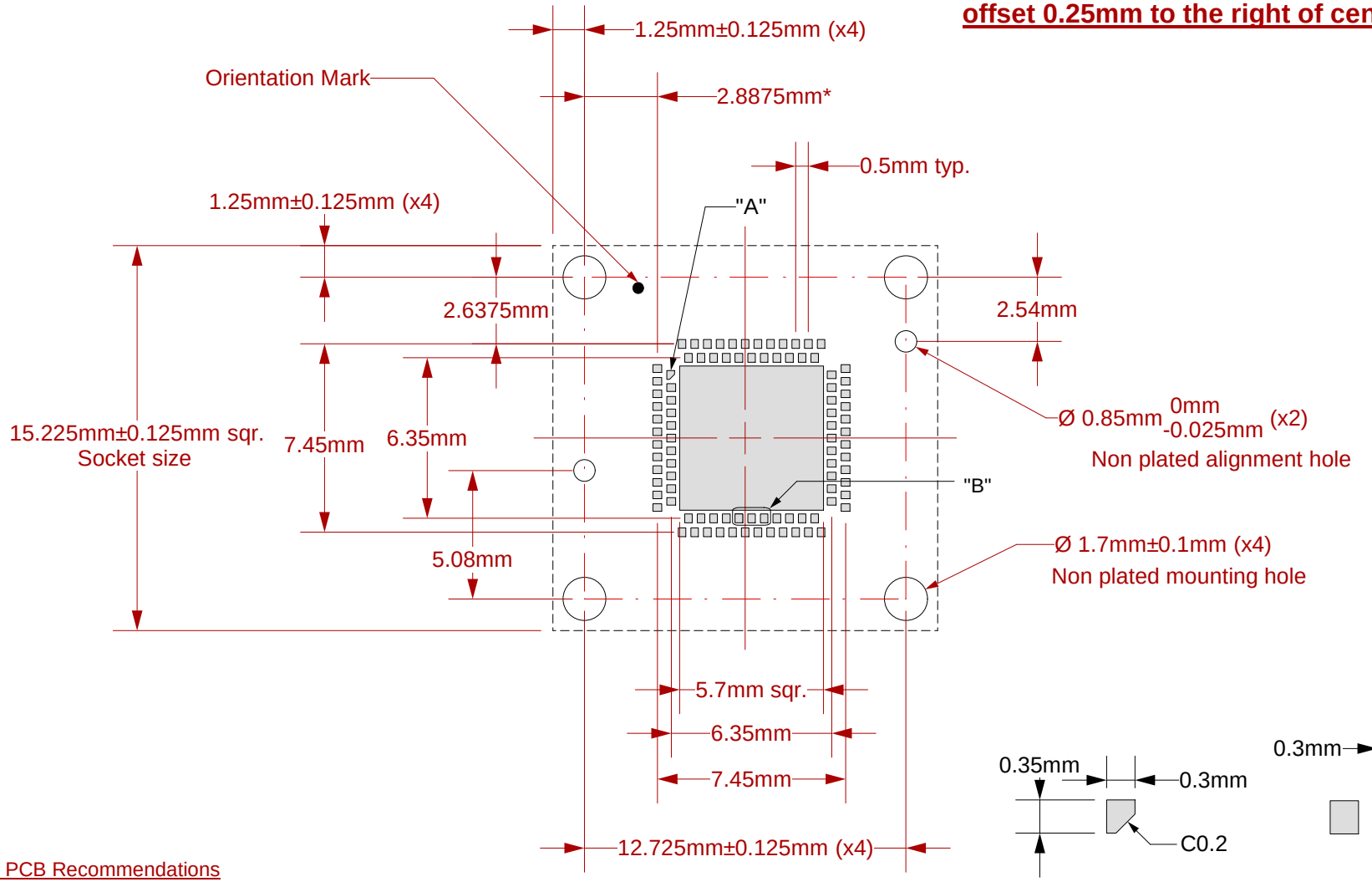
	File: SG-MLF-7014 Dwg	Modified: 11/11/14	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

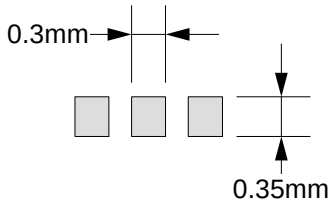
Recommended PCB Layout
Top View

IC package: ASE 92L BCC+

***Note: BCC pattern is NOT symmetrical with respect to the mounting holes. It is offset 0.25mm to the right of center.**



DETAIL "A" (x1)



DETAIL "B" (x91)

Target PCB Recommendations
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

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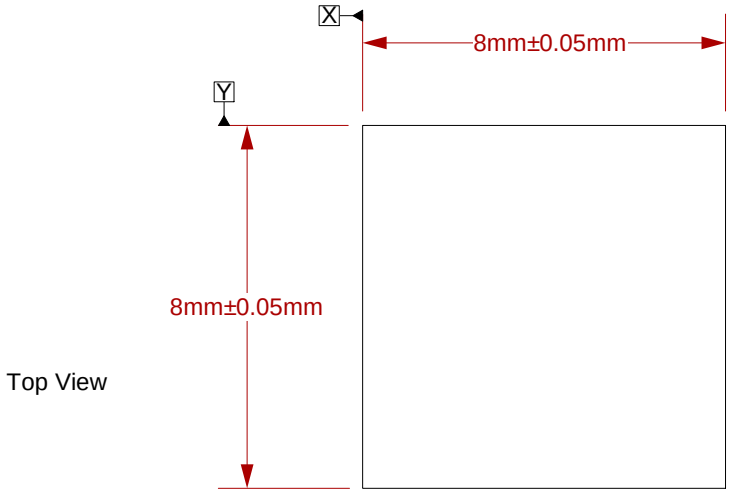
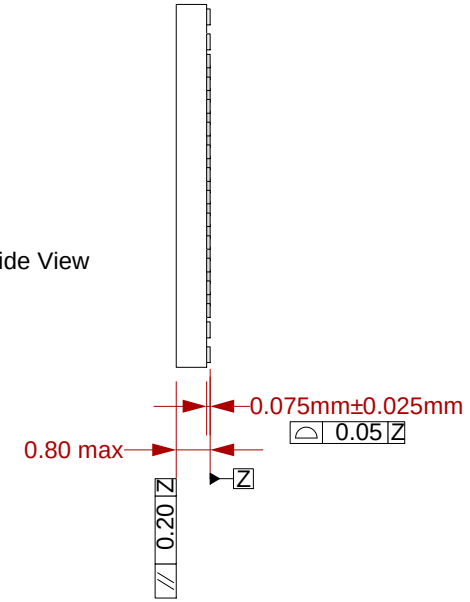
Recommended PCB Layout Tolerances:
±0.025mm [±0.001"] unless stated otherwise.

IC package: ASE 92L BCC+

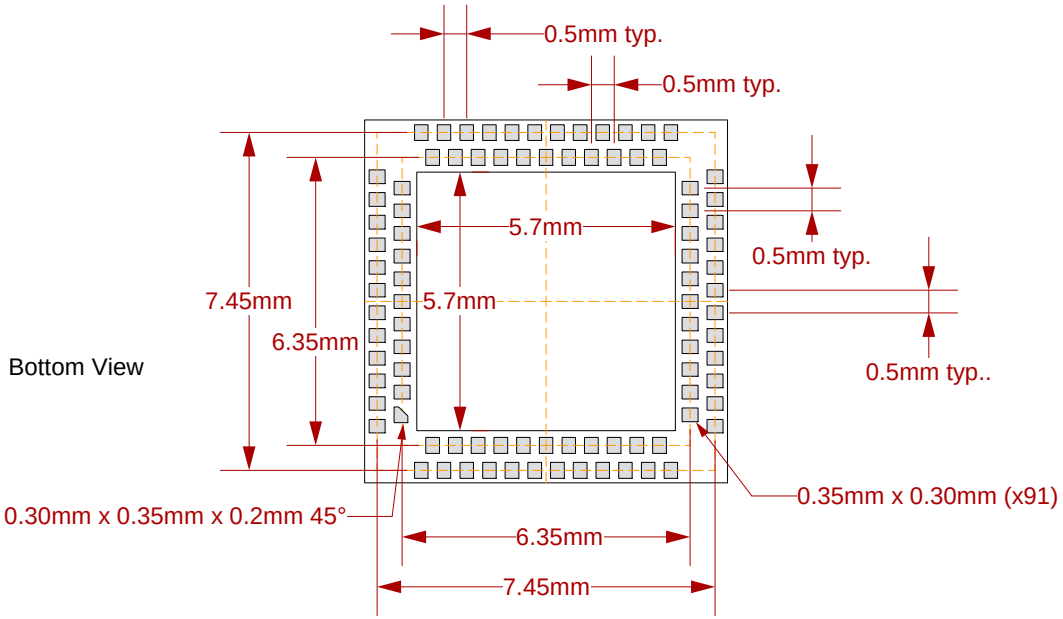
Modified: 10/4/10



Top View



Side View



Bottom View

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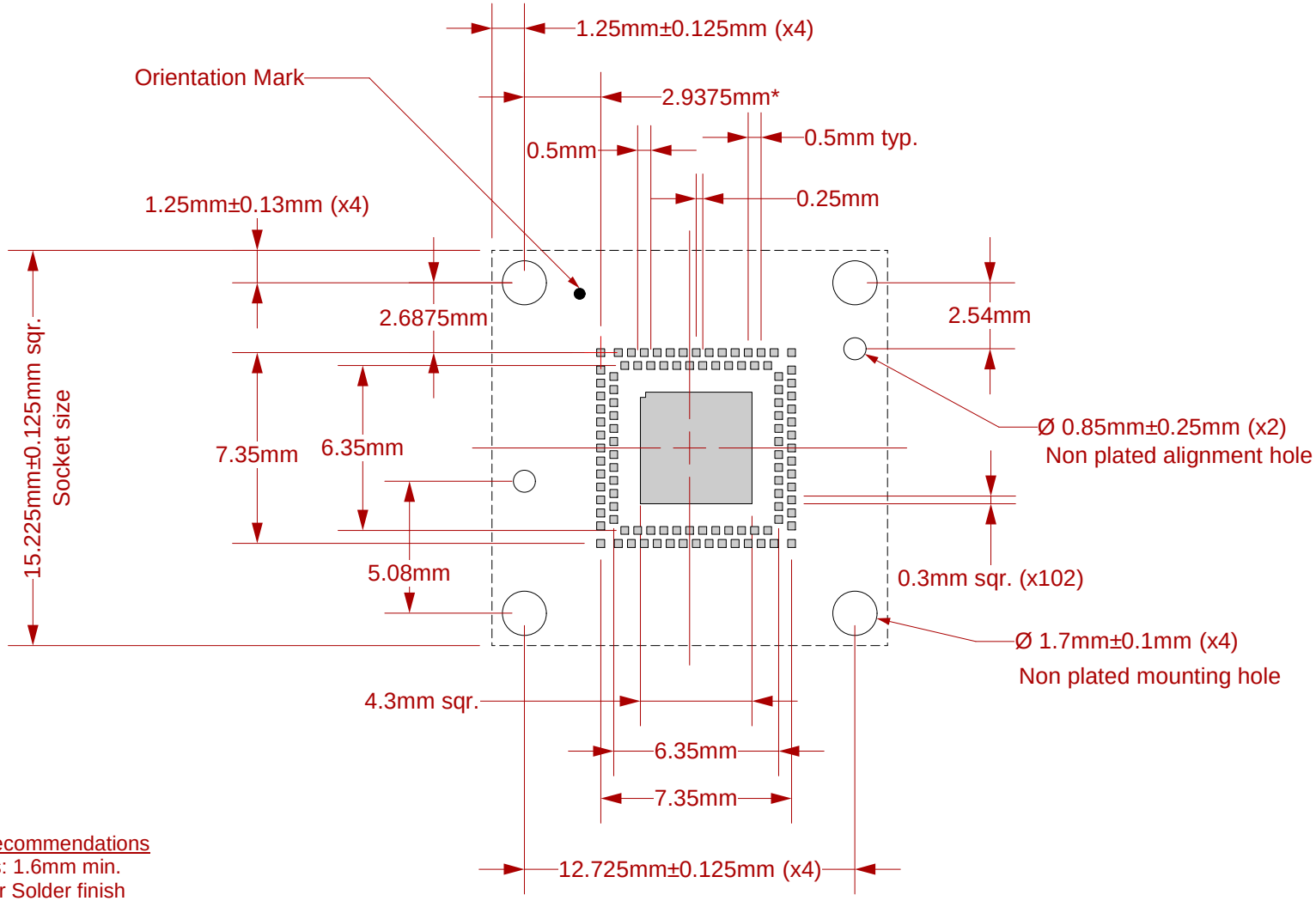
	File: SG-MLF-7014 Dwg	Modified: 11/11/14	

Recommended PCB Layout
Top View

IC package: ASE 102L aQFN

***Note: BCC pattern is not symmetrical with respect to the mounting holes. It is offset 0.25mm to the right of center.**



Target PCB Recommendations
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

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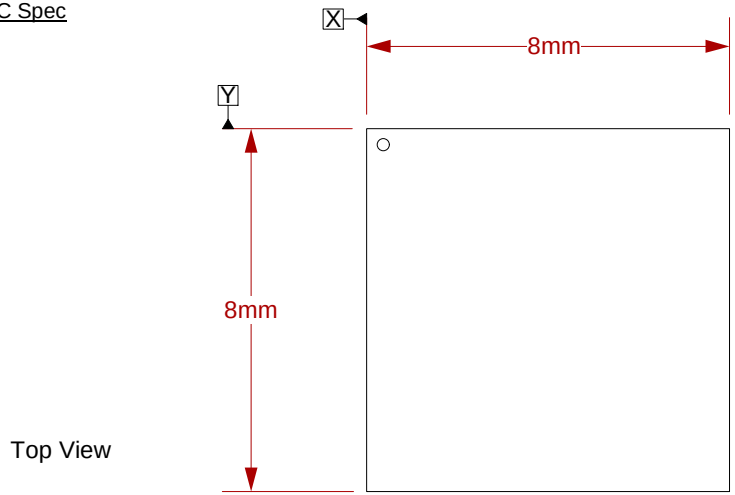
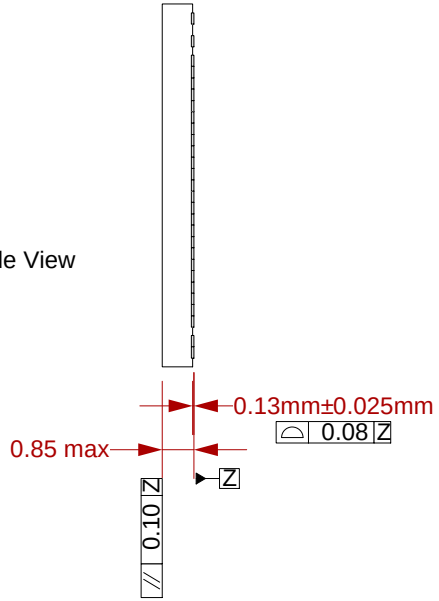
Compatible BCC Spec

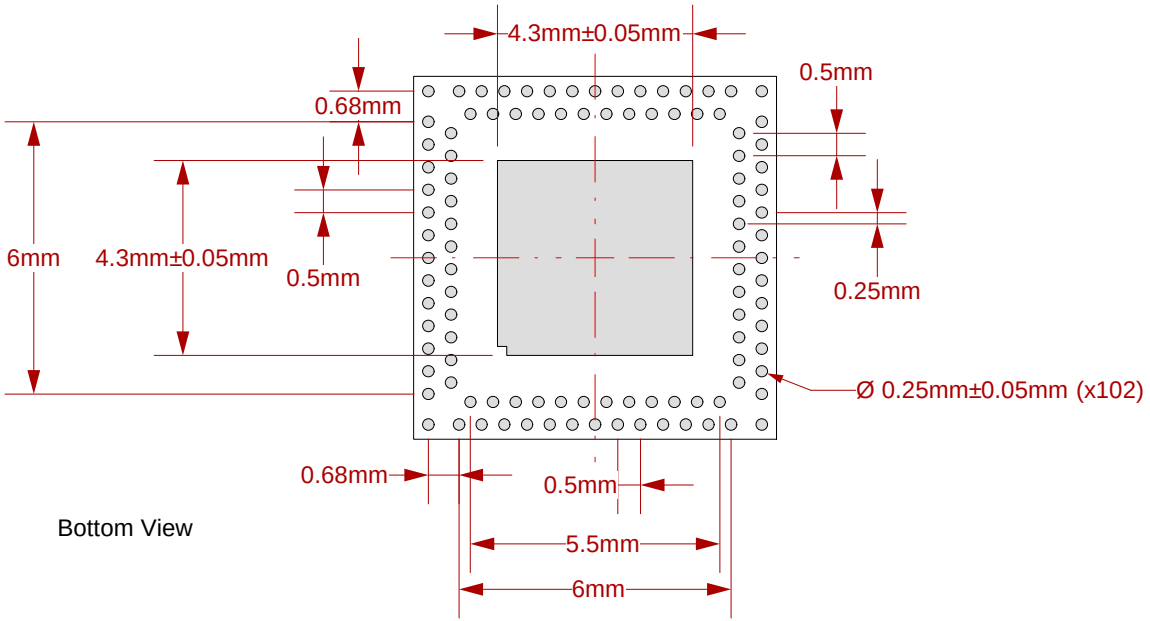
IC package: ASE 102L aQFN



Top View



Side View



Bottom View

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